Product / Package Information

Package:	WLCSP
Body Size (mm):	
I/O Count:	8
Terminal Finish	SnAgCu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.77E-03	100.00	1000000	66.41	664116

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.07 E-04	96.80	968000	30.33	303265
Tin & its alloys	Silver	7440-22-4	2.17 E-05	2.60	26000	0.81	8146
Tin & its alloys	Copper	7440-50-8	5.00 E-06	0.60	6000	0.19	1880
Subtotal			8.34E-04	100.00	1000000	31.33	313290

UBM

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.73E-05	65.23	652287	0.65	6509
Nickel & its alloys	Nickel	7440-02-0	6.80E-06	25.59	255892	0.26	2554
Other inorganic materials	Titanium	7440-32-6	2.23E-06	8.39	83907	0.08	837
Nickel & its alloys	Vanadium	7440-62-2	2.10E-07	0.79	7914	0.01	79
Subtotal			2.66 E-05	100.00	1000000	1.00	9979

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Thermoset	Photosensitive Polyimide Resin	Proprietary		30-60			
Other organic materials	Acrylate Ester	Proprietary		5-10			
Others	Proprietary Ingredient(s)	Proprietary		1-5			
Subtotal			3.36E-05	100	1000000	1.26	12615

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.66 E-03**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ADI Proprietary

ANALOG DEVICES